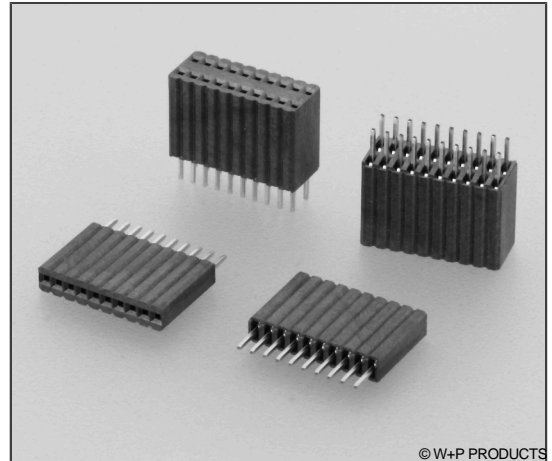


# 46-710 Economy Version

Buchsenleisten RM 1,27x2,54mm, gerade, 1-/2-reihig - Bauhöhe 8,50mm  
 Female Headers, 1.27x2.54mm Pitch, Straight, Single/Double Row – 8.5mm Profile

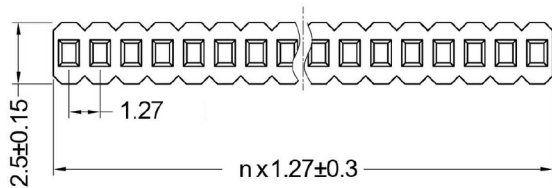
## Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Phosphorbronze
Contact Material	Phosphor bronze
Kontaktoberfläche	Au über Ni
Contact Surface	Au over Ni
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	500 V AC/DC
Test Voltage	500 V AC/DC
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40 °C ~ +105 °C
Temperature Range	-40 °C ~ +105 °C
Verarbeitung	260 °C für 10 sec. / 230 °C für 30-60 sec.
Processing	260 °C for 10 sec. / 230 °C for 30-60 sec.

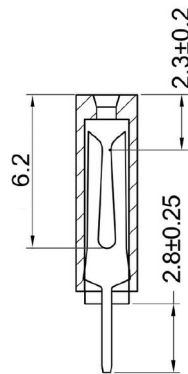
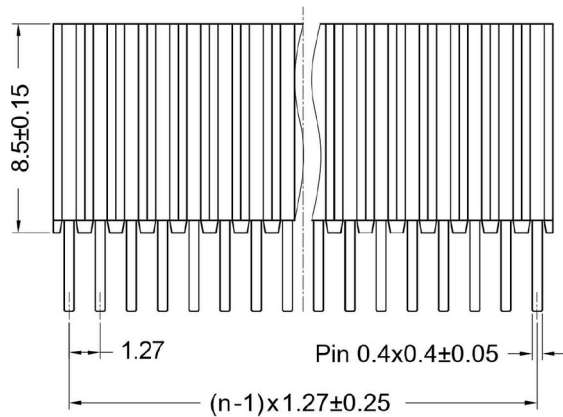
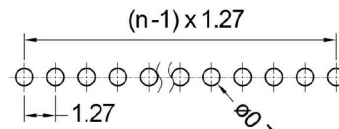


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Geeignet für 0,46mm Vierkantstifte  
 Mates with 0.46mm square pins



Recommended PCB Layout (Top Side)  
 (PCB BOARD TOLERANCE ±0.05)



Series

**46-710**

Contacts\*

**015**

003-040 Einreihig  
 Single row

Rows

**1**

1 Einreihig  
 Single row

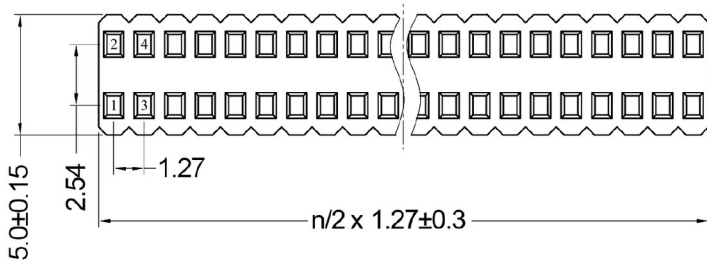
Plating

**00**

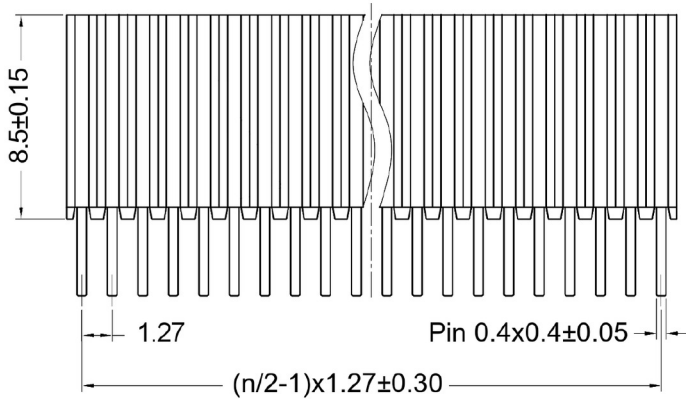
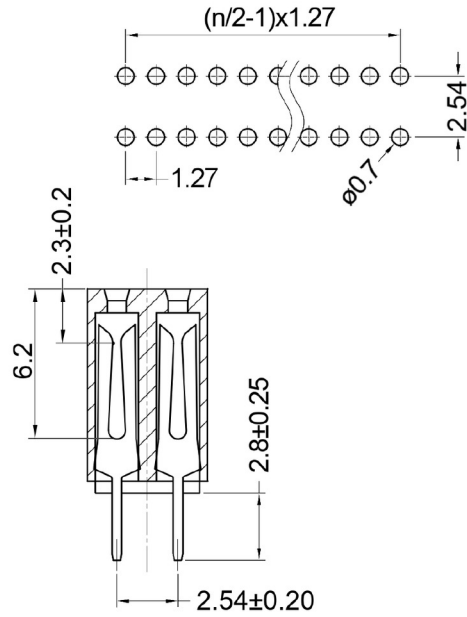
00 Vergoldet  
 Gold plated

# 46-710 Economy Version

Buchsenleisten RM 1,27x2,54mm, gerade, 1-/2-reihig - Bauhöhe 8,50mm  
 Female Headers, 1.27x2.54mm Pitch, Straight, Single/Double Row – 8.5mm Profile



Recommended PCB Layout (Top Side)  
 (PCB BOARD TOLERANCE ±0.05)



Series

**46-710**

Contacts\*

**040**

006-100 Zweireihig  
 Double row

Rows

**2**

2 Zweireihig  
 Double row

Plating

**00**

00 Vergoldet  
 Gold plated

\* Dies ist ein **Bestellbeispiel** -  
 bitte durch Ihre Spezifikationen ersetzen.  
 \* This is an **order example** -  
 please replace by your specifications.

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	untere Temperaturangabe [°C]
Verweildauer oberhalb $T_L$	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	Lower Temperature [°C]
Duration above $T_L$	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

